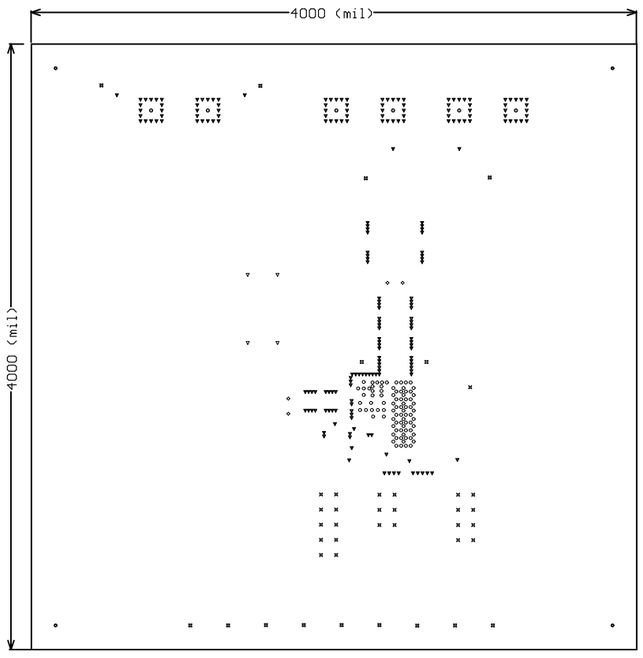
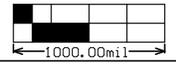
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	2.80mil		
4	Dielectric1	FR-4	9.00mil	4.8	
5	Mid-Layer 1	Copper	2.80mil		
6	Dielectric4	FR-4	9.00mil	4.8	
7	Mid-Layer 2	Copper	2.80mil		
8	Dielectric3	FR-4	9.00mil	4.8	
9	Mid-Layer 3	Copper	2.80mil		
10	Dielectric5	FR-4	9.00mil	4.8	
11	Mid-Layer 4	Copper	2.80mil		
12	Dielectric2	FR-4	9.00mil	4.8	
13	Bottom Layer	Copper	2.80mil		
14	Bottom Solder	Solder Resist	0.40mil	3.5	
15	Bottom Overlay				





Symbol	Quantity	Finished Hole Size	Plated	Hole Type	Drill Layer Pair	Hole Tolerance
○	85	7.87mil (0.200mm)	PTH	Round	Top Layer - Bottom Layer	
▼	206	8.00mil (0.203mm)	PTH	Round	Top Layer - Bottom Layer	
◇	4	29.53mil (0.750mm)	PTH	Round	Top Layer - Bottom Layer	
▽	4	33.46mil (0.850mm)	PTH	Round	Top Layer - Bottom Layer	
⌑	25	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	
⌬	6	62.99mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
⊠	15	63.00mil (1.600mm)	PTH	Round	Top Layer - Bottom Layer	
◘	4	125.00mil (3.175mm)	NPTH	Round	Top Layer - Bottom Layer	
	349 Total					

DESIGN INFORMATION

MIN. TRACK WIDTH: 8 MIL
MIN. CLEARANCE: 0.2 mm
MIN. VIA PAD SIZE: 24 MIL
MINIMUM ANNULAR RING 0.05mm (2MIL) EXTERNAL
PER IPC-D-275 CLASS 2 LEVEL C
REGISTRATION TOLERANCES: METAL +/- 5 MIL, HOLES +/- 3 MIL
HOLE SIZE TOLERANCE (UNLESS OTHERWISE SPECIFIED): +/- 3 MIL

MATERIAL:
[ ] FR-408 [X] FR-4 High Tg [ ] OTHER
THICKNESS: [X] 62 MIL (1.6mm) +/-10% [ ] OTHER
TOLERANCE: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-
BOW & TWIST: [X] ANSI IPC-6012 TYPE 3 CLASS 2
[ ] OTHER +/-

DRILLING:
REFERENCE: [X] AS SHOWN [X] NC_DRILL FILES
PTH COPPER THICKNESS: [X] 20-30 um [ ] OTHER

BOARD FINISH:
SILKSCREEN: [X] TOP [X] BOTTOM
SILKSCREEN COLOR: [X] WHITE [ ] OTHER
SOLDER RESIST COLOR: [X] GREEN [ ] OTHER
[X] MATTE [ ] SEMI-GLOSS
SURFACE FINISH: [X] IMMERSION GOLD (ENIG) [ ] ENEPIG
[ ] IMM. TIN/SILVER OR EQUIV [ ] OTHER OSP (Entek)
ARRAY/PANEL: [ ] CUT AND TRIM PER M1 BOARD OUTLINE
[ ] N.C. ROUTE [X] V. SCORE
CERTIFICATION: MATERIALS AND WORKMANSHIP FOR ALL PCBS TO MEET OR EXCEED THE REQUIREMENTS OF:
[X] ANSI IPC-A-600F CLASS -> [ ] 1 [X] 2 [ ] 3
[X] RoHS [ ] OTHER PER ORDER
ALL BOARDS MUST MEET OR EXCEED UL94-V0 REQUIREMENTS.
PCB MUST BEAR THE UL94V-0 UL REGISTERED MATERIAL ID NUMBER

ADDITIONAL REQUIREMENTS:
MICROSECTION: [ ] YES
BARE BOARD ELEC. TEST: [ ] NONE [X] REQUIRED [ ] PER ORDER

TEXAS INSTRUMENTS

PROJECT TITLE: TPSM846C24EVM-006
DESIGNED FOR: Public Release
FILE NAME: BSR006A.PcbDoc

ALL ARTWORK VIEWED FROM TOP SIDE	BOARD #: BSR006	REV: A	SVN REV: Not In VersionControl
LAYER NAME = [illegible]ions	TID #:		
PLOT NAME = Fabrication Drawing	GENERATED : 4/18/2017 10:04:26 AM		TEXAS INSTRUMENTS

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ENGINEER:	LAYOUT BY:
Jason Arrigo	Jim McTeague
SCALE: 1.00	ALTIUM DESIGNER VERSION: 16.0.1.132